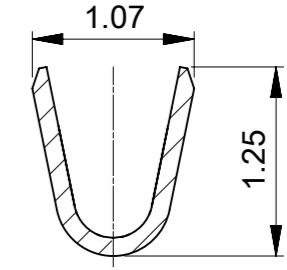


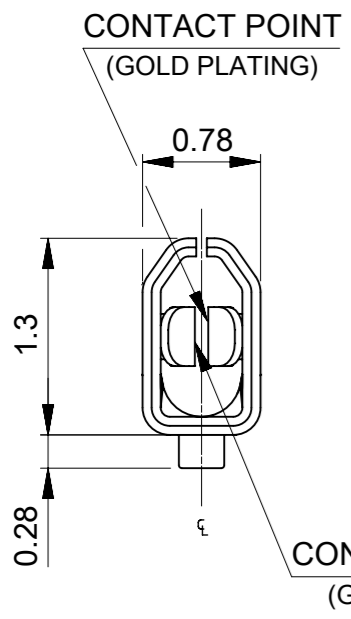
SECTION A-A



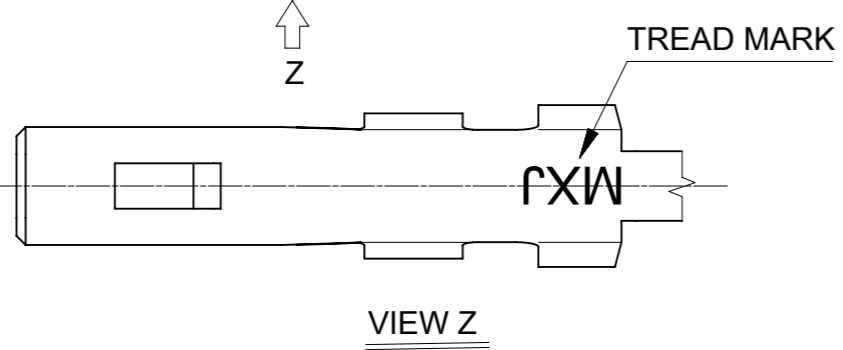
SECTION B-B

NOTES:

- 適合ハウジング: 501189****
APPLICABLE 501330****
HOUSING 501939****
- めっき仕様: 表題欄参照
PLATING: SEE TABLE
- 本製品はコンタクト部 金めっき品である。
THIS PRODUCT IS GOLD PLATING FOR CONTACT POINT.
- 本製品はバレル外面 錫めっき品である。
THIS PRODUCT IS TIN PLATING OUTSIDE A BARREL.
- 圧着条件については、
圧着仕様書(CS-501193-001)を参照願います。
PLEASE REFER TO CRIMP SPECIFICATION (CS-501193-001).
- 製品の取扱いについては、コネクタ取扱い
説明書(5013300000 PS A00,A01)を参照願います。
PLEASE REFER TO INSTRUCTION MANUAL(5013300000 PS A00,A01).



CONTACT POINT (GOLD PLATING)



VIEW Z

1.27µm MIN.	0.9µm MIN.	0.76µm MIN.	5011935100	バラ状 LOOSE
		0.38µm MIN.	5011935000	連鎖状 CHAIN
1.0µm MIN.		0.1µm MIN.	5011936100	バラ状 LOOSE
			5011936000	連鎖状 CHAIN
			5011933000	連鎖状 CHAIN
下地: ニッケルめっき UNDER PLATING: NICKEL PLATING	バレル外側: 錫めっき OUTSIDE OF BARREL: TIN PLATING	接点部: 金めっき CONTACT AREA: GOLD PLATING	オーダー番号 ORDER NO.	端子形状 FORM
めっき仕様(前めっき): PLATING(PRE-PLATING)				

MATERIAL りん青銅 下地ニッケル、部分金めっき、錫めっき品 PHOSPHOR BRONZE t=0.12, SELECTIVE GOLD PLATING, SELECTIVE TIN PLATING, UNDER NICKEL PLATING	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	CURRENT REV DESC: OBSOLETE PART NUMBER AS PER PCN#509451		molex PICO-CLASP 1.0 W/B CONN CRIMP REC TERM (GOLD PLATING)							
	FINISH SEE NOTE	SCALE 20:1	GENERAL TOLERANCES (UNLESS SPECIFIED)				EC NO: 686785 DRWN: SUGEEB 2021/09/07 CHK'D: GGA 2022/02/28 APPR: GGA 2022/02/28				
WIRE RANGE AWG#28-32	INITIAL REVISION: DRWN: QHE31 2017/04/03 APPR: TKANEKO 2017/04/06	ANGULAR TOL ± 3.0°	4 PLACES ± 0.2	3 PLACES ± 0.2	2 PLACES ± 0.2	1 PLACE ± 0.2	0 PLACES ± 0.2	DOCUMENT NUMBER 5011930000	DOC TYPE PSD	DOC PART 000	REVISION C1
INS. RANGE Ø0.4-0.8	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING A3-SIZE	SERIES 501193	MATERIAL NUMBER SEE TABLE	CUSTOMER	SHEET NUMBER 1 OF 1				